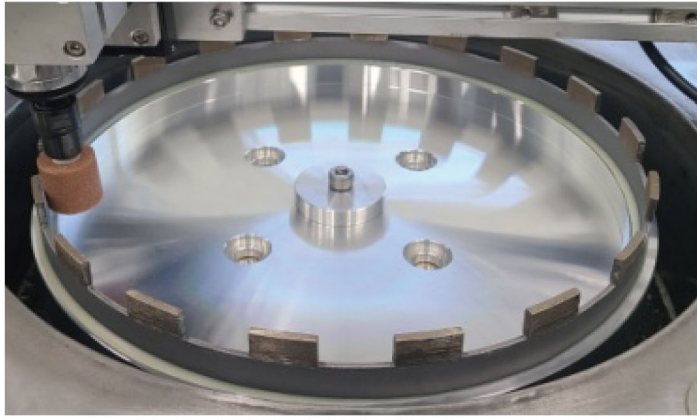


Si / SiC PARTS GRINDING WHEEL

CORE WHEEL

Tips : Electroplated, Sintered, Brazed



ELECTROPLATED GRINDING WHEEL

for Rough Grinding



• **Applications**

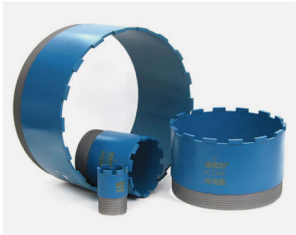
Used for coring the center of a Si, SiC Plate to create a ring-shaped structure.

• **Characteristics & Advantages**

- Manufactured for many different processing purposes with various tool shapes.
- Different types of bond upon customer's requirement and target performance. (Tips : Electroplated, Sintered, Brazed)
- Field proven consistent quality performance.

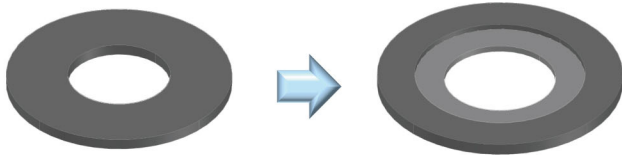
• **Wheel Types**

Manufactured with various different shapes and materials to meet the lifespan, grinding ability and dimensional accuracy.



• **Applications**

Used for making various different shapes on the Si Focus ring such as outer diameter, inner arbor and taper etc.



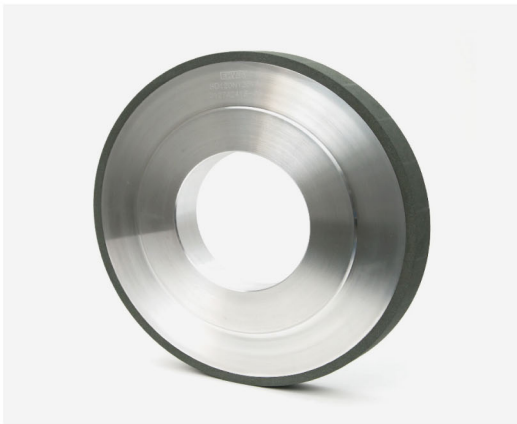
• **Wheel Types**

It is possible to manufacture a wide variety of tool designs that can be used for processing to meet customer's needs such as chamfering, hole grinding, arbor grinding and tapping etc.



VITRIFIED / RESIN GRINDING WHEEL

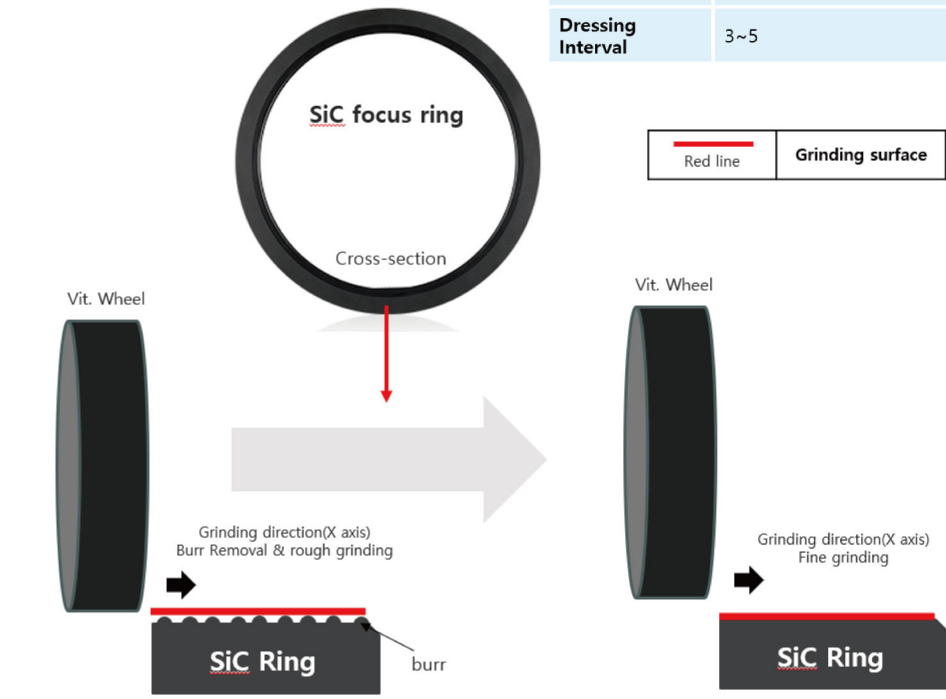
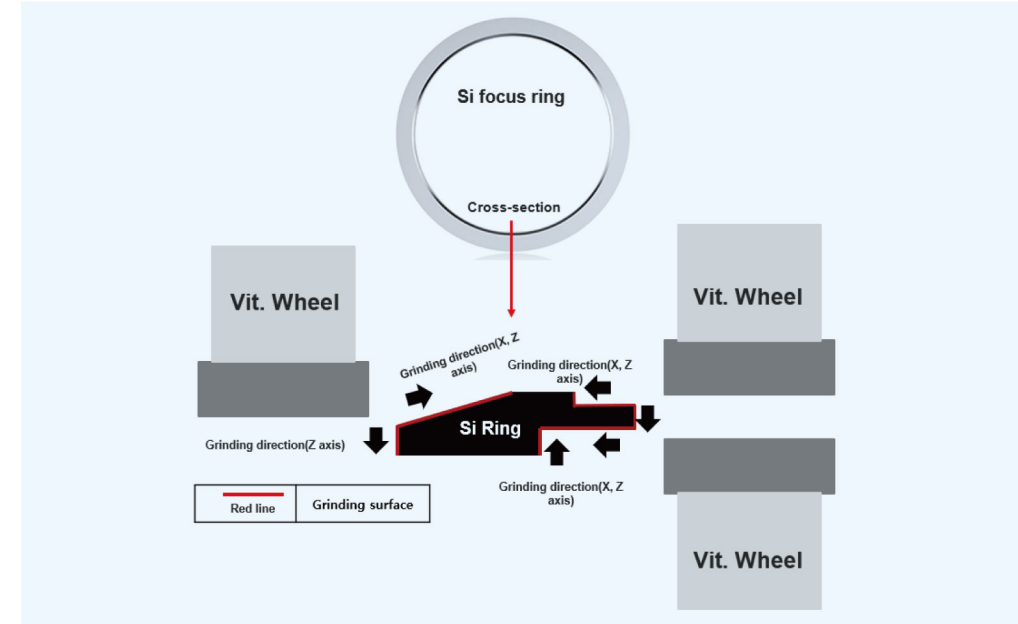
for Fine Grinding



Wheel size	VD-14A1_305D-35T-5X-30U-127H
Machine	Rotary surface grinding machine
Wheel Spec.	D120N125VD, D600N125VA, D800N125VA
Wheel Speed	50~70m/s
Workpiece	Sintered SiC or CVD-SiC
Coolant	Emulsion
Roughness (Request Roughness)	After grinding, Ra 0.10~0.05
RPM of Table	-
Feed rate	Rough 1500mm/min
Dresser	SiC #80
Dressing system	-
Dressing Amount	-
Dressing Interval	3~5

• **Applications**

Used for making various different shapes on the Si, SiC Focus ring such as outer diameter, inner arbor and taper etc.



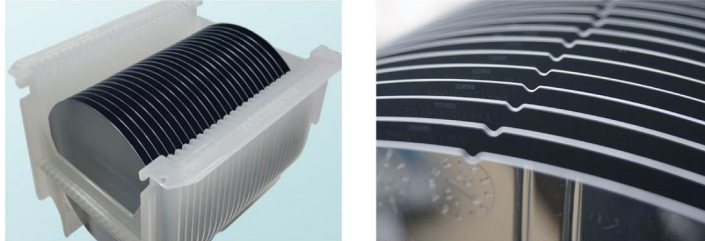
Si / SiC WAFER EDGE, NOTCH WHEEL



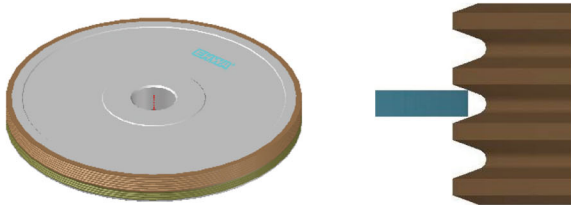
• **Advantages**

- Various groove shapes can be designed
- Grinded with uniform chamfer width (excellent rigidity)
- Strong groove shape retention
- Product 1ea enables multi-stage grinding (rough / fine grinding)

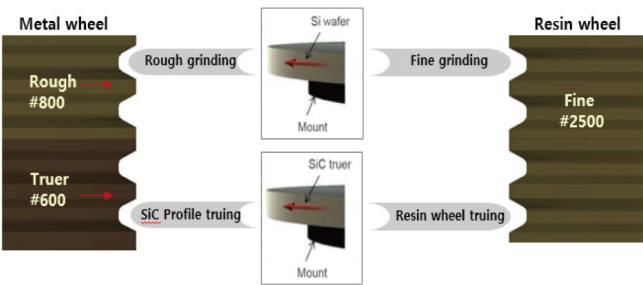
• **Applications**



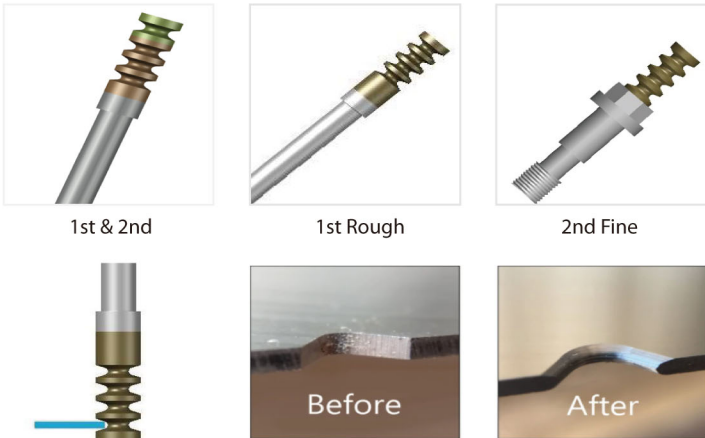
• **Wheel Shape**



• **12" Wafer Grinding Process**



• **Wheel Shape : Notch grinding process**



- **100D ~ 300D**
- **Mesh : #400 ~ #3000**
- **Application : Edge grinding**

- **3.2D ~ 4.2D**
- **Mesh : #400 ~ #3000**
- **Application : Notch Grinding**

